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PATENT AND TRADEMARK FACSIMILE COVER SHEET

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below:

Date: 2-18-03

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To: Patent and Trademark Office
 Att: Examiner Scott B. Geyer
 Fax: 1-703-872-9319
 No. of pages: 12

From: Stetina Brunda Garred & Brucker
 Attorney: Mark B. Garred
 Reg. No. 34,823
 Re: Case No.: AMKOR-048A
 Patent Application No.: 09/687,495
 Applicant: Sean Timothy Crowley, et al.
 Filed: 10/13/2000
 Title: SEMICONDUCTOR PACKAGE

PLEASE HAND DELIVER TO: Examiner Scott B. Geyer

Case No.: AMKOR-048A
Patent Appln.

#22D Audit
M. Johnson
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Sean Timothy Crowley et al.)
Serial No.: 09/687,495) Group No.: 2829
Filed: 10/13/2000) Examiner: Geyer, Scott B.
For: SEMICONDUCTOR PACKAGE)

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. §1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D.C. 20231

Dear Sir/Madam:

In response to the final Office Action mailed November 19, 2002, in relation to the above-identified patent application, please amend the application as follows:

In the Claims:

Please amend the following claims:

1. (Four Times Amended) A semiconductor package, comprising:

a semiconductor chip having an upper surface provided with a plurality of input/output pads thereon;

a chip paddle adjacent a bottom surface of the semiconductor chip, said chip paddle having an upper surface and a lower surface;

a plurality of leads surrounding the chip paddle and having upper and lower surfaces, wherein the chip paddle has a maximum thickness which exceeds a maximum